# Power MOSFET 500 mA, 60 V

N-Channel SOT-23

#### **Features**

- AEC Q101 Qualified MVBF170LT1
- These Devices are Pb-Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	60	Vdc
Drain-Gate Voltage	$V_{DGS}$	60	Vdc
Gate-Source Voltage - Continuous - Non-repetitive ( $t_p \le 50 \ \mu s$ )	V <sub>GS</sub> V <sub>GSM</sub>	±20 ±40	Vdc Vpk
Drain Current – Continuous – Pulsed	I <sub>D</sub> I <sub>DM</sub>	0.5 0.8	Adc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1.) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.



## ON Semiconductor®

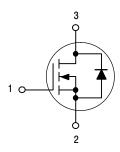
http://onsemi.com

500 mA, 60 V  $R_{DS(on)} = 5 \Omega$ 

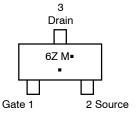


SOT-23 CASE 318 STYLE 21

#### N-Channel



# MARKING DIAGRAM & PIN ASSIGNMENT



6Z = Specific Device Code

M = Date Code ■ Pb-Free Package

(Note: Microdot may be in either location)

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

## **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

	Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS	3		•	•	•	
Drain-Source Breakdown	n Voltage (V <sub>GS</sub> = 0, I <sub>D</sub> = 100 μA)	V <sub>(BR)DSS</sub>	60	-	Vdc	
Gate-Body Leakage Cur	I <sub>GSS</sub>	-	10	nAdc		
ON CHARACTERISTICS	(Note 1)					
Gate Threshold Voltage (	V <sub>GS(th)</sub>	0.8	3.0	Vdc		
Static Drain-Source On-	r <sub>DS(on)</sub>	-	5.0	Ω		
On-State Drain Current (	I <sub>D(off)</sub>	-	0.5	μΑ		
DYNAMIC CHARACTERI	STICS					
Input Capacitance (V <sub>DS</sub> = 10 Vdc, V <sub>GS</sub> = 0	C <sub>iss</sub>	-	60	pF		
SWITCHING CHARACTERISTICS (Note 1)						
Turn-On Delay Time	$(V_{DD} = 25 \text{ Vdc}, I_D = 500 \text{ mA}, R_{qen} = 50 \Omega)$	t <sub>d(on)</sub>	-	10	ns	
Turn-Off Delay Time	Figure 1	t <sub>d(off)</sub>	-	10		

<sup>1.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBF170LT1G	SOT-23 (TO-236) (Pb-Free)	3000 / Tape & Reel
MMBF170LT3G	SOT-23 (TO-236) (Pb-Free)	10000 / Tape & Reel
MVBF170LT1G	SOT-23 (TO-236) (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

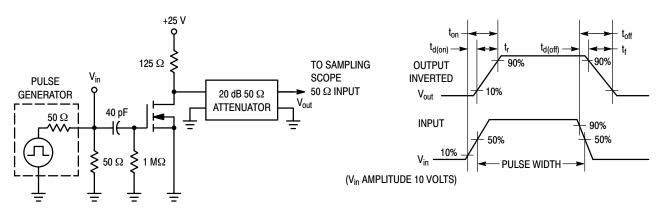
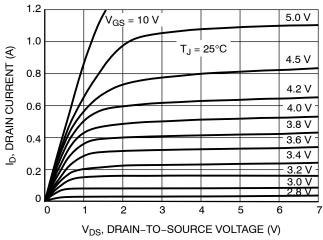


Figure 1. Switching Test Circuit

Figure 2. Switching Waveform

## TYPICAL ELECTRICAL CHARACTERISTICS



V<sub>DS</sub>, DRAIN-TO-SOURCE VOLTAGE (V)

Figure 3. On-Region Characteristics

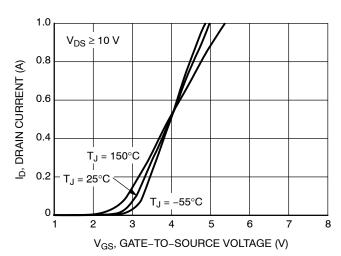


Figure 4. Transfer Characteristics

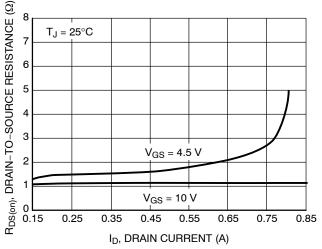


Figure 5. On-Resistance vs. Drain Current and Gate Voltage

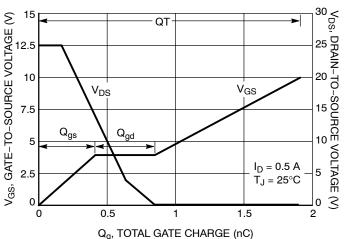


Figure 6. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

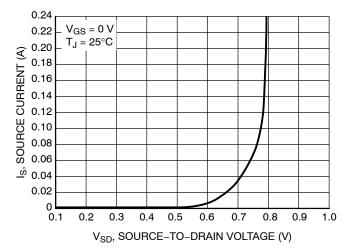


Figure 7. Diode Forward Voltage vs. Current

## TYPICAL ELECTRICAL CHARACTERISTICS

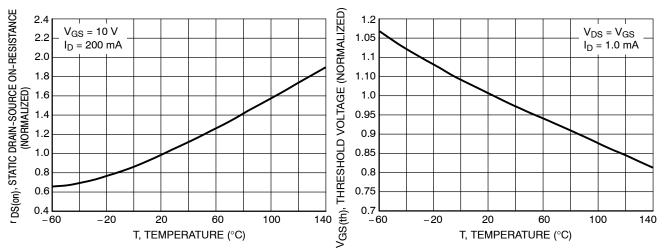
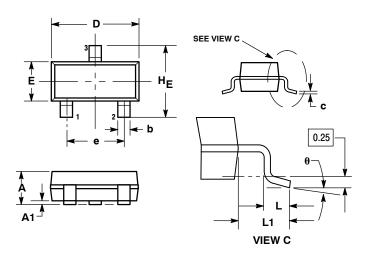


Figure 8. Temperature versus Static Drain-Source On-Resistance

Figure 9. Temperature versus Gate Threshold Voltage

## PACKAGE DIMENSIONS

## SOT-23 (TO-236) CASE 318-08 **ISSUE AP**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

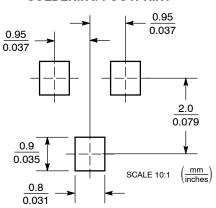
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
  THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS

	MILLIMETERS INCHE		INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 21: PIN 1. GATE

2. SOURCE DRAIN

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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